ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1					Form Type * Distribute	* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Mater					ials and Mfg Information				
upplier Informa	tion														
Company name*			Company unique ID			J	Unique ID Authority					Response Date*			
nsemi											2023-06-08				
Contact Name			Title - Contact			I	Phone - Contact*				Email - Contact*				
Product-Env-Stewar	ds		Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com				
uthorized Represent	tative*	Title - Representative			I	Phone - Representative*				Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com				
Requester	Requester Item Number		Mfr Item Number Mfr Item Name			Effecti		Version	N	Manufacturing Site	W	eight*	UOM	Unit Type	
		NSM3005NZTAG MEA Small Signal		BJT and MOSI	FET	2023-06-08 MY1		MY1	5.0	08	mg	Each			
	roccess Information		orminal Pess	Alloy	STD-020 MSL	Poting	Dook Proc	ng Pody T	Comporation	May Time at Peals	Tomporetw	o Numb	er of Reflow Cyc	Jac	
			Terminal Base Alloy J-STD-02 CU Alloy 1		S1D-020 MSL	Kaung	Peak Process Body Tempera 260 C		Т,				er of Reflow Cyc	ries	
	(Sn) - annealed	C	U Alloy	1			200		JC	30	seconds	3			
omments	no of work townsur-t	dunina c-1	domina ia 10 °	20 seconds											
	ne at peak temperature														
or more information	ı regarding material con	nposition p	olease refer t	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Itaalian applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.08	mg	Supplier	Silicon (Si)	7440-21-3		0.08	mg
Die Attach	0.08	mg		Epoxy resin	proprietary data		0.002	mg
			Supplier	Silver (Ag)	7440-22-4		0.0676	mg
			Supplier	Phenolic Resin	Proprietary Data		0.002	mg
			Supplier	Inorganic filler	Proprietary Data		0.002	mg
			Supplier	Dicyandiamine	461-58-5		0.0004	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.006	mg
Lead Frame	2.62	mg	Supplier	Silver (Ag)	7440-22-4		0.0524	mg
			Supplier	Tin (Sn)	7440-31-5		0.0065	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0058	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0065	mg
			Supplier	Copper (Cu)	7440-50-8		2.5487	mg
Mold Compound-Black	2.02	mg	Supplier	Epoxy and Phenolic Resin	40216-08-8		0.1616	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0101	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.0404	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1.7473	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0606	mg
Plating	0.25	mg	Supplier	Tin (Sn)	7440-31-5		0.25	mg
Wire Bond - Au	0.03	mg	Supplier	Gold (Au)	7440-57-5		0.03	mg